



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Bollinger, et al.

**SERIAL NO.:** 

10/719,829

FILING DATE:

20-Nov-2003

TITLE:

Method For Picking Semiconductor Chips From A Foil

**EXAMINER:** 

Unassigned

ART UNIT:

Unassigned

## **CERTIFICATE OF MAILING**

I hereby certify that this paper is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandría, VA/22313-1450, on the date

printed below:

Name:

Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450

## STATUS INQUIRY LETTER

Please advise of the status for the above-identified patent application.

Respectfully submitted, Thelen Reid & Priest LLP

David B. Ritchie

Reg. No. 31,562

Thelen Reid & Priest LLP P.O. Box 640640 San Jose, CA 95164-0640 (408) 292-5800 (4080287-8040 (Fax)